

Gallium Nitride 28V, 5W RF Power Transistor

Built using the SIGANTIC® NRF1 process - A proprietary GaN-on-Silicon technology

FEATURES

- Optimized for CW, pulsed, WiMAX, W-CDMA, LTE, and other applications from DC to 6GHz
- 100% RF Tested at 2500MHz
- 5W P3dB CW Power
- 15.5dB Power Gain
- Low cost, surface mount SOIC package
- High reliability gold metallization process
- Lead-free and RoHS compliant
- Subject to EAR99 Export Control



**DC - 6000MHz
5 Watt, 28 Volt
GaN HEMT**



2-Tone Specifications: $V_{DS} = 28V$, $I_{DQ} = 50mA$, Frequency = 2500MHz, Tone spacing = 1MHz, $T_C = 25^\circ C$
Measured in Nitronex Test Fixture

| Symbol | Parameter | Min | Typ | Max | Units |
|---------------|--|------|------|-----|-------|
| $P_{1dB,PEP}$ | Peak Envelope Power at 1dB Compression | 5.0 | 7.5 | - | W |
| G_{SS} | Small Signal Gain | 14.5 | 15.5 | - | dB |
| P_{IMD3} | Peak Envelope Power at -35dBc IMD3 | - | 2.5 | - | W |
| η | Drain Efficiency at 3dB Compression | 55 | 60 | - | % |

RF Performance (CW): $V_{DS} = 28V$, $I_{DQ} = 50mA$, Frequency = 2500MHz, $T_C = 25^\circ C$, Measured in Nitronex Test Fixture

| Symbol | Parameter | Typ | Units |
|-----------|---|-----|-------|
| P_{3dB} | Average Output Power at 3dB Compression | 5.1 | W |
| P_{1dB} | Average Output Power at 1dB Compression | 2.9 | W |
| η | Drain Efficiency at 3dB Compression | 56 | % |

OFDM Performance: $V_{DS} = 28V$, $I_{DQ} = 100mA$, Single carrier OFDM waveform 64-QAM 3/4, 8 burst, continuous frame data, 3.5 MHz channel bandwidth. Peak/Avg. = 10.3dB @ 0.01% probability on CCDF. Frequency = 3500MHz, $P_{OUT,AVG} = 24dBm$, $T_C = 25^\circ C$. Measured in Load Pull System

| Symbol | Parameter | Typ | Units |
|--------|------------------------|------|-------|
| G_p | Power Gain | 11.2 | dB |
| η | Drain Efficiency | 9 | % |
| EVM | Error Vector Magnitude | 1.0 | % |

DC Specifications: $T_C=25^\circ\text{C}$

| Symbol | Parameter | Min | Typ | Max | Units |
|----------------------------|---|------|------|------|----------|
| Off Characteristics | | | | | |
| V_{BDS} | Drain-Source Breakdown Voltage ($V_{GS} = -8\text{V}$, $I_D = 2\text{mA}$) | 100 | - | - | V |
| I_{DLK} | Drain-Source Leakage Current ($V_{GS} = -8\text{V}$, $V_{DS} = 60\text{V}$) | - | 0.5 | 2 | mA |
| On Characteristics | | | | | |
| V_T | Gate Threshold Voltage ($V_{DS} = 28\text{V}$, $I_D = 2\text{mA}$) | -2.0 | -1.5 | -1.0 | V |
| V_{GSQ} | Gate Quiescent Voltage ($V_{DS} = 28\text{V}$, $I_D = 50\text{mA}$) | -1.8 | -1.3 | -0.8 | V |
| R_{ON} | On Resistance ($V_{GS} = 2\text{V}$, $I_D = 15\text{mA}$) | - | 2.0 | 2.2 | Ω |
| I_D | Drain Current ($V_{DS} = 7\text{V}$ pulsed, 300 μs pulse width, 0.2% duty cycle, $V_{GS} = 2\text{V}$) | 1.1 | 1.3 | - | A |

Absolute Maximum Ratings: Not simultaneous, $T_C=25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Max | Units |
|---------------|---|------------|---------------------------|
| V_{DS} | Drain-Source Voltage | 100 | V |
| V_{GS} | Gate-Source Voltage | -10 to 3 | V |
| P_T | Total Device Power Dissipation (Derated above 25°C) | 7.6 | W |
| θ_{JC} | Thermal Resistance (Junction-to-Case) | 23 | $^\circ\text{C}/\text{W}$ |
| T_{STG} | Storage Temperature Range | -65 to 150 | $^\circ\text{C}$ |
| T_J | Operating Junction Temperature | 200 | $^\circ\text{C}$ |
| HBM | Human Body Model ESD Rating (per JESD22-A114) | 1A (>250V) | |
| MM | Machine Model ESD Rating (per JESD22-A115) | M1(>50V) | |
| MSL | Moisture Sensitivity Level (per IPC/JEDEC J-STD-020): Rating of 3 at 260°C Package Peak Temperature | | |

Load-Pull Data, Reference Plane at Device Leads

$V_{DS}=28V, T_A=25^{\circ}C$ unless otherwise noted

Table 1: Optimum Source and Load Impedances ($V_{DS} = 28V$)

| Frequency | $Z_S (\Omega)$ | $Z_L (\Omega)$ | $I_{DQ} (mA)$ | Optimized Tuning Condition |
|-----------|----------------|----------------|---------------|---|
| 900 | $9.2 + j23.8$ | $52.6 + j22.8$ | 50 | CW Power and Efficiency |
| 1800 | $5.2 + j0.5$ | $24.5 + j18.3$ | 50 | CW Power and Efficiency |
| 2140 | $5.0 - j2.6$ | $17.1 + j15.0$ | 50 | CW Power and Efficiency |
| 2500 | $5.4 - j10.5$ | $14.7 + j10.0$ | 50 | CW Power and Efficiency |
| 3500 | $5.0 - j21.0$ | $11.2 + j4.7$ | 50 | CW Power and Efficiency |
| 900 | $21.9 + j43.4$ | $59.5 + j33.7$ | 100 | W-CDMA, P_{OUT} , Efficiency, -45dBc ACPR |
| 1800 | $13.1 + j24.3$ | $34.5 + j48.8$ | 100 | W-CDMA, P_{OUT} , Efficiency, -45dBc ACPR |
| 2140 | $5.4 + j17.3$ | $25.4 + j36.4$ | 100 | W-CDMA, P_{OUT} , Efficiency, -45dBc ACPR |
| 2600 | $4.0 + j6.8$ | $12.2 + j25.8$ | 100 | LTE, P_{OUT} , Efficiency, -45dBc ACPR |
| 2500 | $5.0 + j16.2$ | $13.2 + j20.4$ | 100 | OFDM, Maximum P_{OUT} , 1.5% EVM |
| 3500 | $4.1 - j0.6$ | $6.6 + j10.5$ | 100 | OFDM, Maximum P_{OUT} , 1.5% EVM |
| 5100 | $17.8 - j16.4$ | $10.7 - j4.9$ | 100 | OFDM, Maximum P_{OUT} , 1.5% EVM |
| 5200 | $21.5 - j29.0$ | $11.9 - j4.8$ | 100 | OFDM, Maximum P_{OUT} , 1.5% EVM |
| 5700 | $10.2 - j13.2$ | $11.3 - j17.0$ | 100 | OFDM, Maximum P_{OUT} , 1.5% EVM |
| 5800 | $11.0 - j16.3$ | $12.1 - j15.3$ | 100 | OFDM, Maximum P_{OUT} , 1.5% EVM |

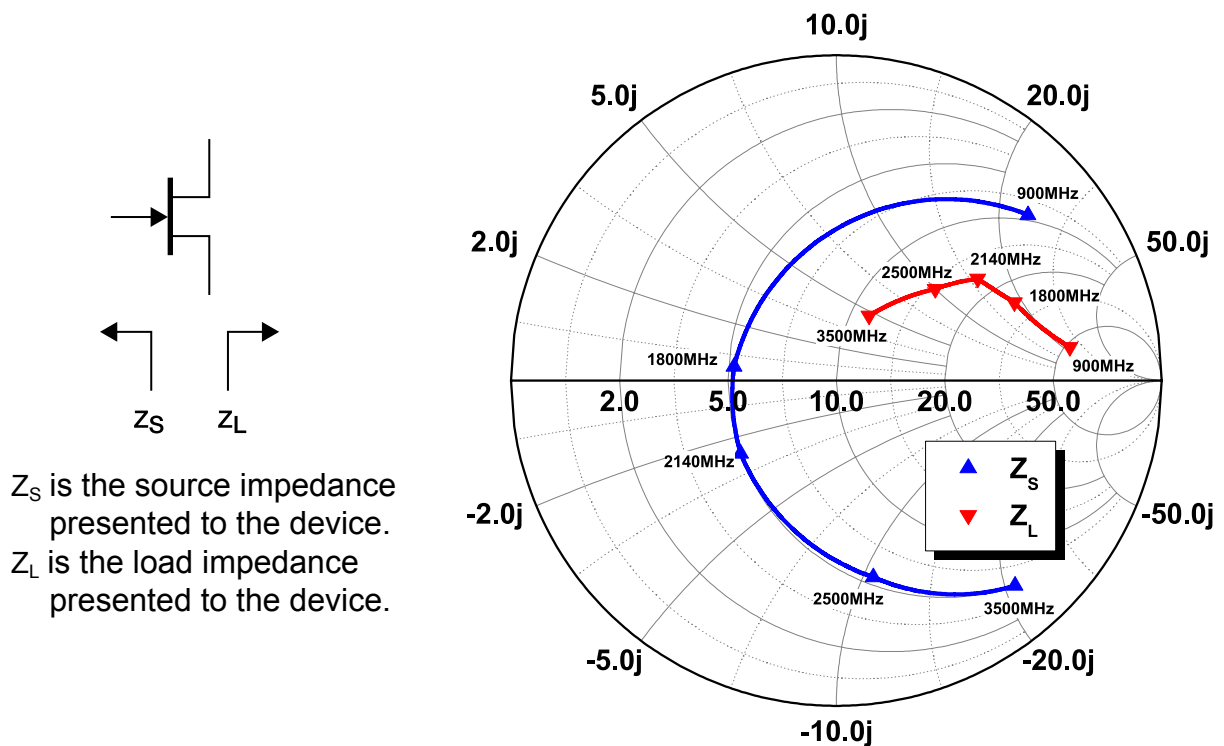


Figure 1 - Impedances for Optimum CW Power, $V_{DS} = 28V, I_{DQ} = 50mA$

Load-Pull Data, Reference Plane at Device Leads

$V_{DS}=28V, I_{DQ}=50mA, T_A=25^{\circ}C$ unless otherwise noted.

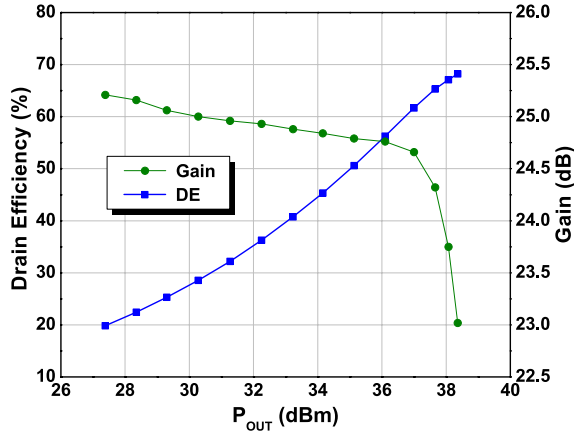


Figure 2 - Typical CW Performance
Frequency = 900MHz

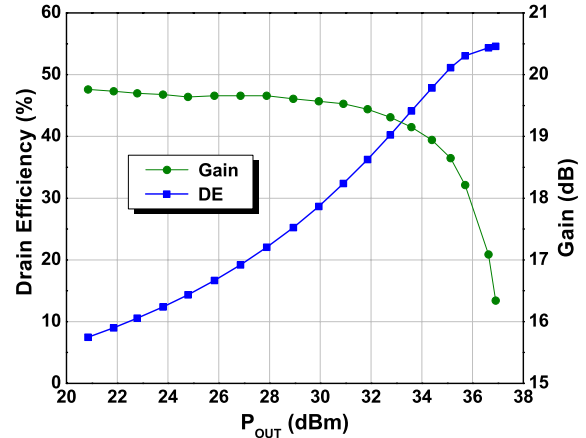


Figure 3 - Typical CW Performance
Frequency = 2500MHz

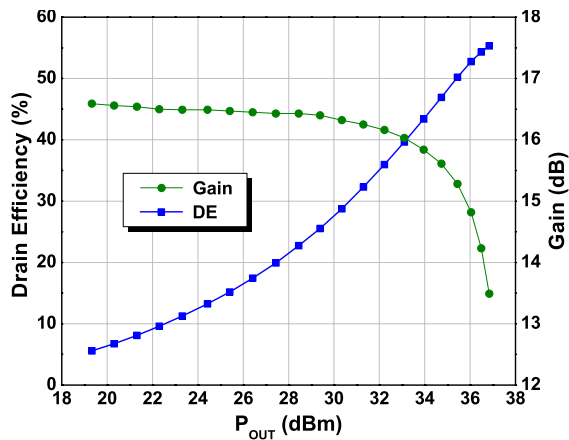


Figure 4 - Typical CW Performance
Frequency = 3500MHz

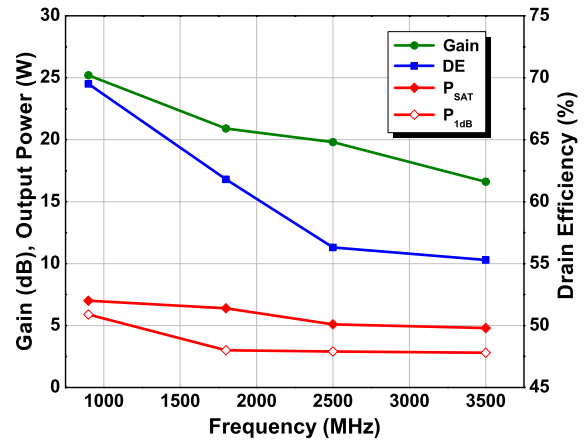


Figure 5 - Typical CW Performance
Frequency = 900 to 3500MHz

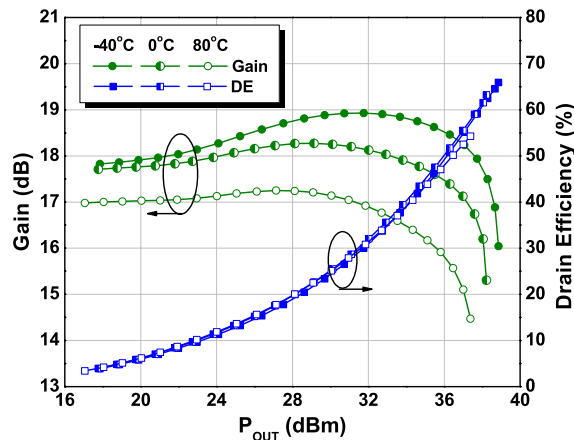


Figure 6 - Typical CW Performance
Over Temperature, Frequency = 2500MHz

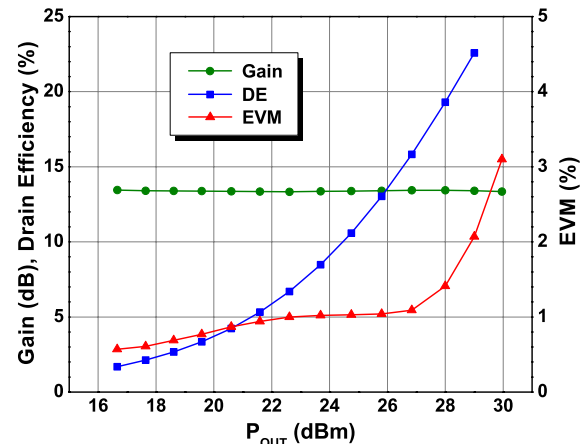


Figure 7 - Typical OFDM Performance
 $I_{DQ} = 100mA$, Frequency = 2500MHz

Load-Pull Data, Reference Plane at Device Leads

$V_{DS}=28V$, $I_{DQ}=50mA$, $T_A=25^{\circ}C$ unless otherwise noted.

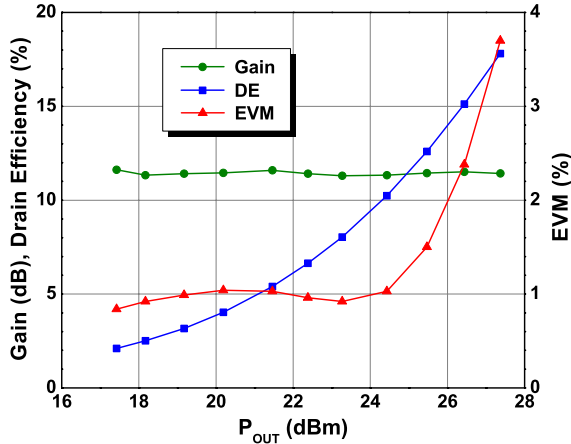


Figure 8 - Typical OFDM Performance
 $I_{DQ} = 100mA$, Frequency = 3500MHz

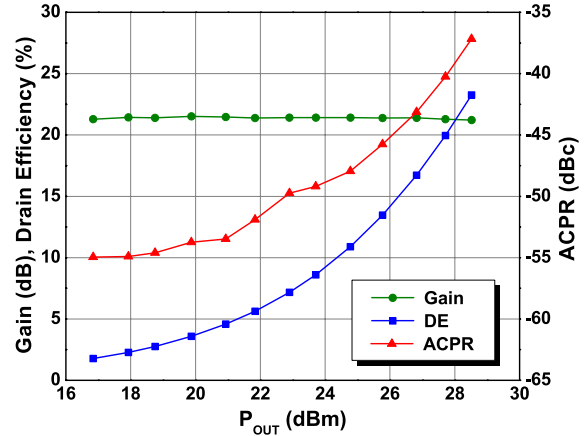


Figure 9 - Typical W-CDMA Performance
 $I_{DQ} = 100mA$, Frequency = 900MHz

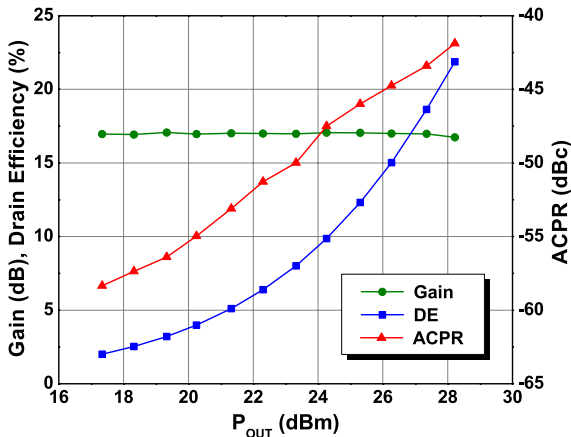


Figure 10 - Typical W-CDMA Performance
 $I_{DQ} = 100mA$, Frequency = 1800MHz

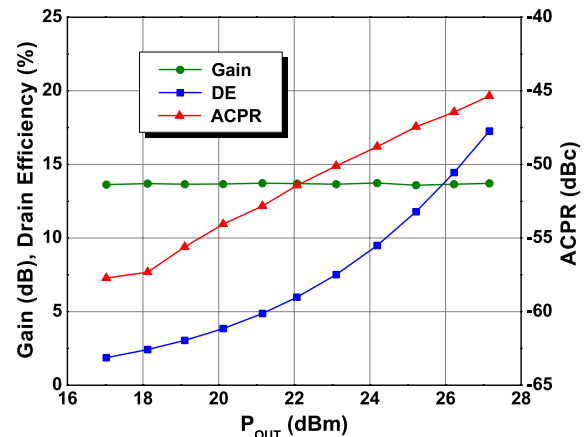


Figure 11 - Typical W-CDMA Performance
 $I_{DQ} = 100mA$, Frequency = 2140MHz

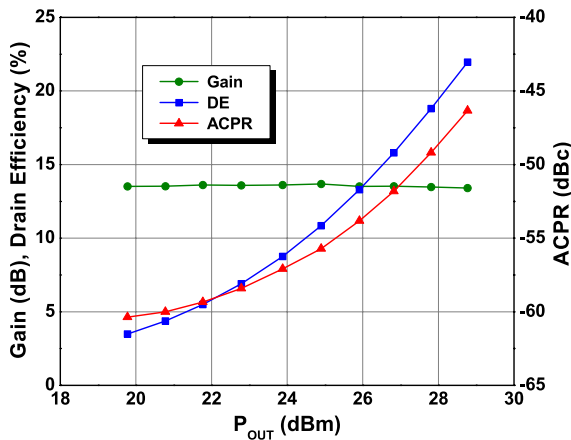


Figure 12 - Typical LTE Performance
 $I_{DQ} = 100mA$, Frequency = 2600MHz

Typical Device Characteristics

$V_{DS}=28V$, $I_{DQ}=50mA$, $T_A=25^{\circ}C$ unless otherwise noted.

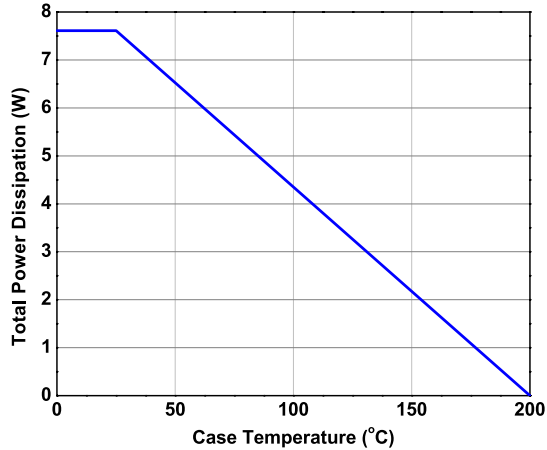


Figure 13 - Power Derating Curve

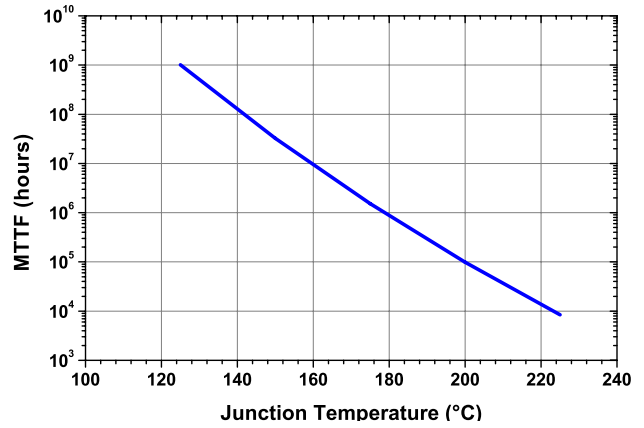


Figure 14 - MTTF of NRF1 Devices as a Function of Junction Temperature

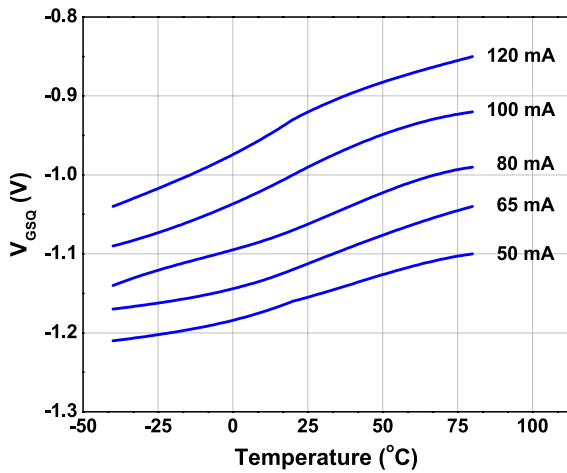


Figure 15 - Quiescent Gate Voltage (V_{GSQ}) Required to Reach $I_{DQ} = 50mA$ as a Function of Ambient Temperature

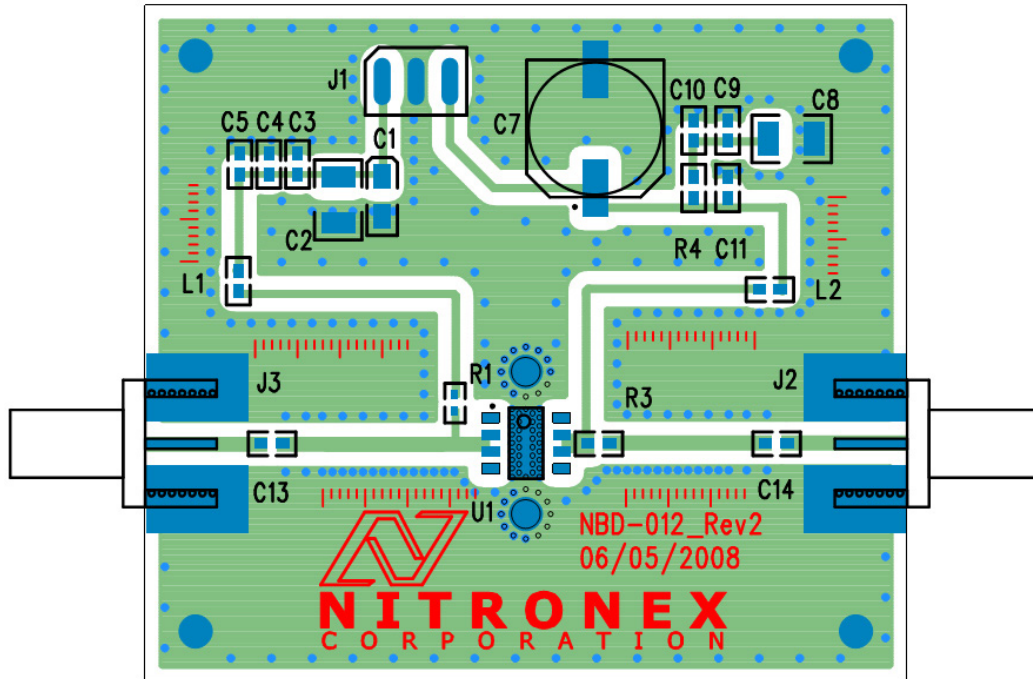


Figure 16 - APP-NPTB00004-25 2500MHz Demonstration Board

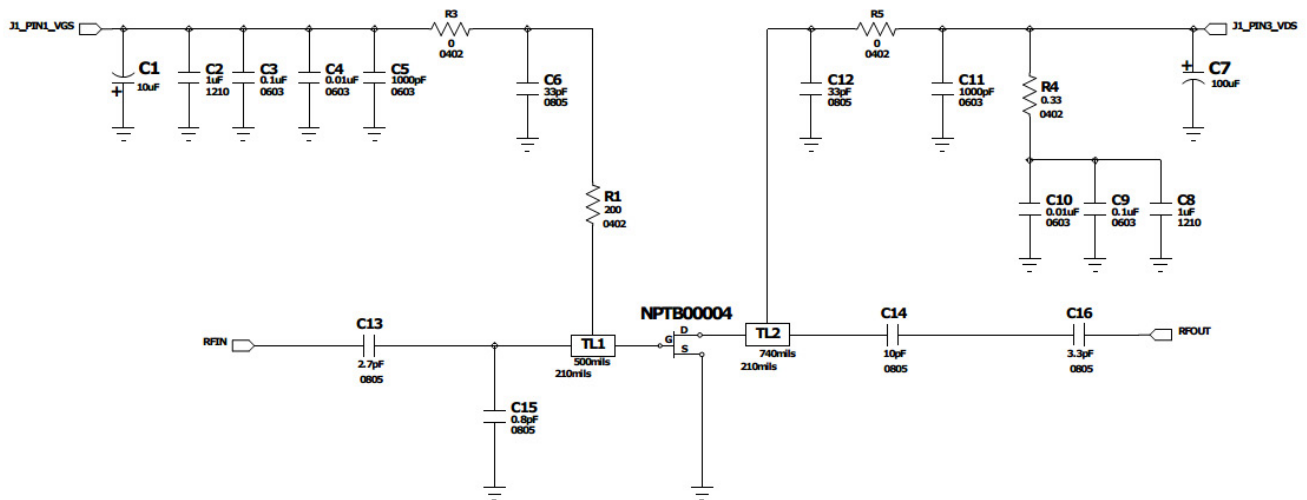


Figure 17 - APP-NPTB00004-25 2500MHz Demonstration Board Equivalent Circuit

Table 2: APP-NPTB00004-25 2500MHz Demonstration Board Bill of Materials

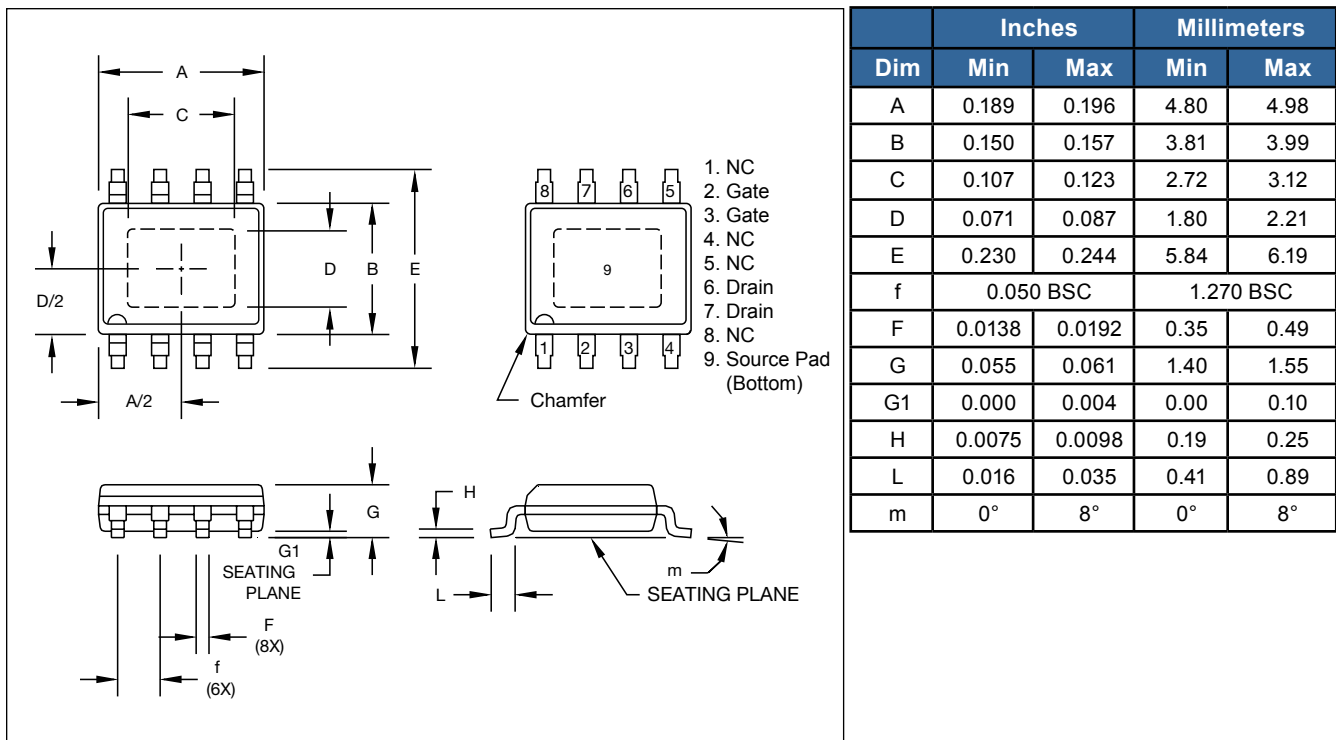
| Name | Value | Tolerance | Vendor | Vendor Number |
|--------------|-----------|-----------|--------------------------|--------------------------------------|
| C1 | 10uF | 20% | AVX | TAJA106M016R |
| C2 | 1uF | 10% | AVX | 12101C105KAT2A |
| C3 | 0.1uF | 10% | Murata | GRM188R72A104KA35D |
| C4 | 0.01uF | 10% | AVX | 06031C103KAT2A |
| C5 | 0.001uF | 10% | AVX | 06031C102KAT2A |
| C6 | 33pF | 5% | ATC | ATC600F330B |
| C7 | 100uF | 20% | Panasonic | ECE-V1JA101P |
| C8 | 1uF | 10% | AVX | 12101C105KAT2A |
| C9 | 0.1uF | 10% | Murata | GRM188R72A104KA35D |
| C10 | 0.01uF | 10% | AVX | 06031C103KAT2A |
| C11 | 0.001uF | 10% | AVX | 06031C102KAT2A |
| C12 | 33pF | 5% | ATC | ATC600F330B |
| C13 | 2.7pF | +/- 0.1pF | ATC | ATC600F2R7B |
| C14 | 10pF | 1% | ATC | ATC600F100B |
| C15 | 0.8pF | +/-0.1pF | ATC | ATC600F0R8B |
| C16 | 3.3pF | +/-0.1pF | ATC | ATC600F3R3B |
| R1 | 200 ohm | 1% | Panasonic | ERJ-2GEJ201X |
| R3, R5 | 0 ohm | -- | Panasonic | ERJ-2GE0R00X |
| R4 | 0.033 ohm | 1% | Panasonic | ERJ-6BWJR033W |
| NBD-012_Rev1 | -- | -- | Alberta Printed Circuits | NBD-012_Rev1 |
| Substrate | | | Rogers | R04350, t = 30mil $\epsilon_r = 3.5$ |

Ordering Information¹

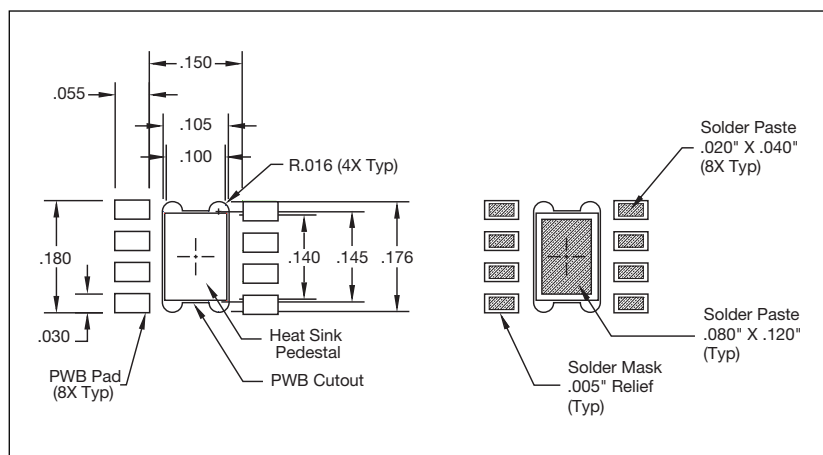
| Part Number | Order Multiple | Description |
|-------------|----------------|---|
| NPTB00004DT | 97 | Tube; NPTB00004 in D (PSOP2) Package |
| NPTB00004DR | 1500 | Tape and Reel; NPTB00004 in D (PSOP2) Package |

1: To find a Nitronex contact in your area, visit our website at <http://www.nitronex.com>

D Package Dimensions and Pinout



Mounting Footprints



Nitronex, LLC

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Additional Information

This part is lead-free and is compliant with the RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

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